



INTERNATIONAL STANDARD



**Field device integration (FDI) –
Part 103-1: Profiles – PROFIBUS**

INTERNATIONAL
ELECTROTECHNICAL
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CONTENTS

FOREWORD	4
INTRODUCTION	4
1 Scope	7
2 Normative references	7
3 Terms, definitions, abbreviated terms and acronyms conventions	8
3.1 Terms and definitions	8
3.2 Abbreviated terms and acronyms	8
3.3 Conventions	8
3.3.1 EDDL syntax	8
3.3.2 XML syntax	8
3.3.3 Capitalizations	8
4 Profile for PROFIBUS	9
4.1 General	9
4.2 Catalog profile	9
4.2.1 Protocol support file	9
4.2.2 CommunicationProfile definition	10
4.2.3 Profile device	10
4.2.4 Protocol version information	10
4.3 Associating a Package with a device	11
4.3.1 Device type identification mapping	11
4.3.2 Device type revision mapping	12
4.4 Information Model mapping	13
4.4.1 ProtocolType definition	13
4.4.2 DeviceType mapping	14
4.4.3 FunctionalGroup identification definition	14
4.5 Topology elements	15
4.5.1 ConnectionPoint definition	15
4.5.2 Communication Device definition	17
4.5.3 Communication service provider definition	17
4.5.4 Network definition	18
4.6 Methods	19
4.6.1 Methods for FDI Communication Servers	19
4.6.2 Methods for Gateways	21
Annex A (normative) Topology Scan result schema	27
A.1 General	27
A.2 Network	27
A.3 ProfibusNetworkT	27
A.4 ProfibusConnectionPointT	27
A.5 ProfibusIdentificationT	28
A.6 ProfibusAddressT	29
Annex B (normative) Transfer service parameters	30
B.1 General	30
B.2 sendData	30
B.3 xsreceiveData	30
B.4 xsTransferSendDataT	30
B.5 TransferResultDataT	31

B.6 OperationT.....	31
Bibliography.....	32
Figure 1 – Version mapping problem.....	12
Table 1 – ProtocolSupportFile for FDI Device Packages	9
Table 2 – ProtocolSupportFile for FDI Communication Packages	9
Table 3 – PROFIBUS CommunicationProfile definition schema	10
Table 4 – Catalog values for profile devices.....	10
Table 5 – Version mapping examples.....	11
Table 6 – Device identification information mapping.....	12
Table 7 – Protocol type Profibus_DP	13
Table 8 – Protocol type Profibus_PA.....	14
Table 9 – DeviceType property mapping	14
Table 10 – PROFIBUS Device Types identification attributes.....	14
Table 11 – ConnectionPoint type for Profibus_DP	15
Table 12 – ConnectionPoint type for Profibus_PA.....	16
Table 13 – Method Connect arguments.....	19
Table 14 – Method Disconnect arguments	20
Table 15 – Method Transfer arguments.....	20
Table 16 – Method SetAddress arguments.....	21
Table 17 – Connect service arguments	22
Table 18 – Method Transfer arguments.....	24
Table 19 – Method SetAddress arguments.....	25
Table A.1 – Elements of ProfibusNetworkT	27
Table A.2 – Attributes of ProfibusConnectionPointT	28
Table A.3 – Elements of ProfibusConnectionPointT	28
Table A.4 – Attributes of ProfibusIdentificationT.....	29
Table B.1 – Attributes of TransferSendDataT.....	31
Table B.2 – Attributes of TransferResultDataT	31

INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI) –

Part 103-1: Profiles – PROFIBUS

FOREWORD

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International Standard IEC 62769-103-1 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) support for generic protocol extension for faster adoption of other technologies;
- b) support for Package Developers to build EDDs targeted for today's EDD bases system under a single development tool.

The text of this International Standard is based on the following documents:

CDV	Report on voting
65E/622/CDV	65E/685A/RVC 65E/685/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

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~~The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of patents concerning~~

- ~~a) method for the supplying and installation of device-specific functionalities, see Patent Family DE10357276;~~
- ~~b) method and device for accessing a functional module of automation system, see Patent Family EP2182418;~~
- ~~c) methods and apparatus to reduce memory requirements for process control system software applications, see Patent Family US2013232186;~~
- ~~d) extensible device object model, see Patent Family US12/893,680.~~

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FIELD DEVICE INTEGRATION (FDI) – Part 103-1: Profiles – PROFIBUS

1 Scope

This part of IEC 62769 specifies an FDI profile of IEC 62769 for IEC 61784-1_CP 3/1 (PROFIBUS DP)¹ and IEC 61784-1_CP3/2 (PROFIBUS PA)¹.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

~~IEC 61784-1, Industrial communication networks – Profiles – Part 1: Fieldbus profiles~~

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62541-100:2015, *OPC Unified Architecture - Part 100: Device Interface*

IEC 62769-2², *Field Device Integration (FDI) – Part 2: FDI Client*

~~NOTE 1 – IEC 62769-2 is technically identical to FDI-2022.~~

IEC 62769-4³, *Field Device Integration (FDI) – Part 4: FDI Packages*

~~NOTE 2 – IEC 62769-4 is technically identical to FDI-2024.~~

IEC 62769-5⁴, *Field Device Integration (FDI) – Part 5: FDI Information Model*

~~NOTE 3 – IEC 62769-5 is technically identical to FDI-2025.~~

IEC 62769-7⁵, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

~~NOTE 4 – IEC 62769-7 is technically identical to FDI-2027.~~

PI Order No.: 2.122:2008, *Specification for PROFIBUS – Device Description and Device Integration – Volume 1: GSD, V5.1, July 2008: GSD*; available at <www.profibus.com> [viewed 2018-11-23]

¹ PROFIBUS is the trade name of the non-profit consortium PROFIBUS & PROFINET International. This information is given for the convenience of users of this document and does not constitute an endorsement by IEC of the trademark holder or any of its products. Compliance does not require use of the trade name. Use of the trade name requires permission of the trade name holder.

² Under preparation. Stage at the time of publication: IEC/RFDIS 62769-2:2020.

³ Under preparation. Stage at the time of publication: IEC/RFDIS 62769-4:2020.

⁴ Under preparation. Stage at the time of publication: IEC/RFDIS 62769-5:2020.

⁵ Under preparation. Stage at the time of publication: IEC/RFDIS 62769-7:2020.

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI) –
Part 103-1: Profiles – PROFIBUS**

**Intégration des appareils de terrain (FDI) –
Partie 103-1: Profils – PROFIBUS**

Withdrawing

CONTENTS

FOREWORD	4
1 Scope	6
2 Normative references	6
3 Terms, definitions, abbreviated terms and conventions	6
3.1 Terms and definitions	6
3.2 Abbreviated terms and acronyms	7
3.3 Conventions	7
3.3.1 EDDL syntax	7
3.3.2 XML syntax	7
3.3.3 Capitalizations	7
4 Profile for PROFIBUS	8
4.1 General	8
4.2 Catalog profile	8
4.2.1 Protocol support file	8
4.2.2 CommunicationProfile definition	8
4.2.3 Profile device	9
4.2.4 Protocol version information	9
4.3 Associating a Package with a device	10
4.3.1 Device type identification mapping	10
4.3.2 Device type revision mapping	11
4.4 Information Model mapping	12
4.4.1 ProtocolType definition	12
4.4.2 DeviceType mapping	13
4.4.3 FunctionalGroup identification definition	13
4.5 Topology elements	13
4.5.1 ConnectionPoint definition	13
4.5.2 Communication Device definition	15
4.5.3 Communication service provider definition	16
4.5.4 Network definition	17
4.6 Methods	17
4.6.1 Methods for FDI Communication Servers	17
4.6.2 Methods for Gateways	20
Annex A (normative) Topology Scan result schema	26
A.1 General	26
A.2 Network	26
A.3 ProfibusNetworkT	26
A.4 ProfibusConnectionPointT	26
A.5 ProfibusIdentificationT	27
A.6 ProfibusAddressT	28
Annex B (normative) Transfer service parameters	29
B.1 General	29
B.2 sendData	29
B.3 xsreceiveData	29
B.4 xsTransferSendDataT	29
B.5 TransferResultDataT	30
B.6 OperationT	30

Bibliography.....	31
Figure 1 – Version mapping problem.....	11
Table 1 – ProtocolSupportFile for FDI Device Packages	8
Table 2 – ProtocolSupportFile for FDI Communication Packages	8
Table 3 – PROFIBUS CommunicationProfile definition schema	9
Table 4 – Catalog values for profile devices.....	9
Table 5 – Version mapping examples.....	9
Table 6 – Device identification information mapping.....	11
Table 7 – Protocol type Profibus_DP	12
Table 8 – Protocol type Profibus_PA.....	12
Table 9 – DeviceType property mapping	13
Table 10 – PROFIBUS Device Types identification attributes.....	13
Table 11 – ConnectionPoint type for Profibus_DP.....	14
Table 12 – ConnectionPoint type for Profibus_PA.....	15
Table 13 – Method Connect arguments.....	18
Table 14 – Method Disconnect arguments.....	18
Table 15 – Method Transfer arguments.....	19
Table 16 – Method SetAddress arguments.....	20
Table 17 – Connect service arguments.....	21
Table 18 – Method Transfer arguments.....	22
Table 19 – Method SetAddress arguments.....	24
Table A.1 – Elements of ProfibusNetworkT	26
Table A.2 – Attributes of ProfibusConnectionPointT	27
Table A.3 – Elements of ProfibusConnectionPointT	27
Table A.4 – Attributes of ProfibusIdentificationT.....	28
Table B.1 – Attributes of TransferSendDataT	30
Table B.2 – Attributes of TransferResultDataT	30

INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI) –

Part 103-1: Profiles – PROFIBUS

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FIELD DEVICE INTEGRATION (FDI) –

Part 103-1: Profiles – PROFIBUS

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IEC 62541-100:2015, *OPC Unified Architecture - Part 100: Device Interface*

IEC 62769-22, *Field Device Integration (FDI) - Part 2: FDI Client*

IEC 62769-4³, *Field Device Integration (FDI) – Part 4: FDI Packages*

IEC 62769-54, *Field Device Integration (FDI) – Part 5: FDI Information Model*

IEC 62769-7⁵, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

PI Order No.: 2.122:2008, *Specification for PROFIBUS – Device Description and Device Integration – Volume 1: GSD, V5.1, July 2008: GSD*; available at <www.profibus.com> [viewed 2018-11-23]

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⁵ Under preparation. Stage at the time of publication: IEC/RFDIS 62769-7:2020.

SOMMAIRE

AVANT-PROPOS	34
1 Domaine d'application	36
2 Références normatives	36
3 Termes, définitions, abréviations et conventions	37
3.1 Termes et définitions	37
3.2 Abréviations et acronymes	37
3.3 Conventions	37
3.3.1 Syntaxe EDDL	37
3.3.2 Syntaxe XML	37
3.3.3 Majuscules	37
4 Profil pour PROFIBUS	38
4.1 Généralités	38
4.2 Profil de catalogue	38
4.2.1 Fichier de prise en charge de protocole	38
4.2.2 Définition de CommunicationProfile	39
4.2.3 Appareil de profil	39
4.2.4 Informations relatives à la version de protocole	39
4.3 Association d'un Paquetage avec un appareil	40
4.3.1 Mapping d'identification du type d'appareil	40
4.3.2 Mapping des révisions de type d'appareil	41
4.4 Mapping du Modèle d'Information	43
4.4.1 Définition de ProtocolType	43
4.4.2 Mapping de DeviceType	43
4.4.3 Définition du FunctionalGroup "Identification"	44
4.5 Eléments de topologie	44
4.5.1 Définition de ConnectionPoint	44
4.5.2 Définition de l'Appareil de Communication	46
4.5.3 Définition du fournisseur de service de communication	47
4.5.4 Définition du Réseau	48
4.6 Méthodes	48
4.6.1 Méthodes pour les Serveurs de Communication FDI	48
4.6.2 Méthodes pour les Passerelles	51
Annexe A (normative) Schéma du résultat du balayage de la topologie	57
A.1 Généralités	57
A.2 Network	57
A.3 ProfibusNetworkT	57
A.4 ProfibusConnectionPointT	57
A.5 ProfibusIdentificationT	58
A.6 ProfibusAddressT	59
Annexe B (normative) Paramètres du service Transfer	60
B.1 Généralités	60
B.2 sendData	60
B.3 xsreceiveData	60
B.4 xsTransferSendDataT	60
B.5 TransferResultDataT	61
B.6 OperationT	61

Bibliographie.....	62
Figure 1 – Problème de mapping des versions.....	42
Tableau 1 – ProtocolSupportFile pour les Paquetages d’Appareils FDI.....	38
Tableau 2 – ProtocolSupportFile pour les Paquetages de Communication FDI.....	39
Tableau 3 – Schéma de définition pour PROFIBUS CommunicationProfile.....	39
Tableau 4 – Valeurs de catalogue pour les appareils de profil.....	39
Tableau 5 – Exemples de mapping de versions.....	40
Tableau 6 – Mapping des informations d’identification d’appareils.....	41
Tableau 7 – Type de protocole Profibus_DP.....	43
Tableau 8 – Type de protocole Profibus_PA.....	43
Tableau 9 – Mapping des propriétés DeviceType.....	43
Tableau 10 – Attributs d’identification pour les types d’appareils PROFIBUS.....	44
Tableau 11 – Type de ConnectionPoint pour Profibus_DP.....	44
Tableau 12 – Type de ConnectionPoint pour Profibus_PA.....	45
Tableau 13 – Arguments de la Méthode Connect.....	49
Tableau 14 – Arguments de la Méthode Disconnect.....	49
Tableau 15 – Arguments de la Méthode Transfer.....	50
Tableau 16 – Arguments de la Méthode SetAddress.....	51
Tableau 17 – Arguments du service Connect.....	52
Tableau 18 – Arguments de la Méthode Transfer.....	53
Tableau 19 – Arguments de la Méthode SetAddress.....	55
Tableau A.1 – Eléments de ProfibusNetworkT.....	57
Tableau A.2 – Attributs de ProfibusConnectionPointT.....	58
Tableau A.3 – Eléments de ProfibusConnectionPointT.....	58
Tableau A.4 – Attributs de ProfibusIdentificationT.....	59
Tableau B.1 – Attributs de TransferSendDataT.....	61
Tableau B.2 – Attributs de TransferResultDataT.....	61

COMMISSION ÉLECTROTECHNIQUE INTERNATIONALE

INTÉGRATION DES APPAREILS DE TERRAIN (FDI) –

Partie 103-1: Profils – PROFIBUS

AVANT-PROPOS

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La Norme internationale IEC 62769-103-1 a été établie par le sous-comité 65E: Les dispositifs et leur intégration dans les systèmes de l'entreprise, du comité d'études 65 de l'IEC: Mesure, commande et automation dans les processus industriels.

Cette deuxième édition annule et remplace la première édition parue en 2015. Cette édition constitue une révision technique.

Cette édition inclut les modifications techniques majeures suivantes par rapport à l'édition précédente:

- a) prise en charge d'extensions de protocoles génériques, pour une adoption plus rapide d'autres technologies;
- b) capacité offerte aux Développeurs de Paquetages d'élaborer des EDD ciblant les systèmes actuels de bases EDD, en exploitant un seul outil de développement.

Le texte de cette Norme internationale est issu des documents suivants:

CDV	Rapport de vote
65E/622/CDV	65E/685A/RVC 65E/685/RVC

Le rapport de vote indiqué dans le tableau ci-dessus donne toute information sur le vote ayant abouti à l'approbation de la présente Norme internationale.

Ce document a été rédigé selon les Directives ISO/IEC, Partie 2.

Une liste de toutes les parties de la série IEC 62769, publiées sous le titre général *Intégration des appareils de terrain (FDI)*, peut être consultée sur le site web de l'IEC.

Le comité a décidé que le contenu de ce document ne sera pas modifié avant la date de stabilité indiquée sur le site web de l'IEC sous "<http://webstore.iec.ch>" dans les données relatives au document recherché. A cette date, le document sera

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INTÉGRATION DES APPAREILS DE TERRAIN (FDI) –

Partie 103-1: Profils – PROFIBUS

1 Domaine d'application

La présente partie de l'IEC 62769 spécifie un profil FDI de l'IEC 62769 pour l'IEC 61784-1_CP 3/1 (PROFIBUS DP)¹ et l'IEC 61784-1_CP 3/2 (PROFIBUS PA)¹.

2 Références normatives

Les documents suivants cités dans le texte constituent, pour tout ou partie de leur contenu, des exigences du présent document. Pour les références datées, seule l'édition citée s'applique. Pour les références non datées, la dernière édition du document de référence s'applique (y compris les éventuels amendements).

IEC 61804 (toutes les parties), *Blocs fonctionnels (FB) pour les procédés industriels et le langage de description électronique de produit (EDDL)*

IEC 62541-100:2015, *Architecture unifiée OPC - Partie 100: Interface d'appareils*

IEC 62769-2², *Intégration des appareils de terrain (FDI) – Partie 2: Client FDI*

IEC 62769-4³, *Intégration des appareils de terrain (FDI) – Partie 4: Paquetages FDI*

IEC 62769-5⁴, *Intégration des appareils de terrain (FDI) – Partie 5: Modèle d'Information FDI*

IEC 62769-7⁵, *Intégration des appareils de terrain (FDI) – Partie 7: Appareils de communication FDI*

Spécification PI N° 2.122:2008, *Specification for PROFIBUS – Device Description and Device Integration – Volume 1. GSD Specification, V5.1, juillet 2008, GSD*; disponible à l'adresse <www.profibus.com> (disponible en anglais seulement) [consultée 2018-11-23]

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² En cours de préparation. Stade au moment de la publication: IEC/RFDIS 62769-2:2020.

³ En cours de préparation. Stade au moment de la publication: IEC/RFDIS 62769-4:2020.

⁴ En cours de préparation. Stade au moment de la publication: IEC/RFDIS 62769-5:2020.

⁵ En cours de préparation. Stade au moment de la publication: IEC/RFDIS 62769-7:2020.